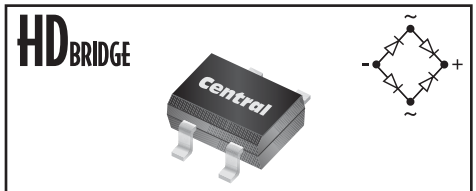
CBRHDSH2-40

SURFACE MOUNT
HIGH DENSITY
2 AMP SILICON
SCHOTTKY BRIDGE RECTIFIER



HD DIP CASE

Central Semiconductor Corp.

www.centralsemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CBRHDSH2-40 is a full wave bridge rectifier mounted in a durable epoxy surface mount molded case, utilizing glass passivated chips.

MARKING CODE: CSH2

FEATURES:

- Low Leakage Current (20μA TYP @ V_{RRM})
- High 2.0A Current Rating
- Low V_F Schottky Diodes (500mV MAX @I_F=2.0A)

MAXIMUM RATINGS: (T_A=25°C unless otherwise noted)	**SYMBOL**		**UNITS**
Peak Repetitive Reverse Voltage	V_{RRM}	40	V
DC Blocking Voltage	V_R	40	V
RMS Reverse Voltage	$V_{R(RMS)}$	28	V
Average Forward Current	I_O	2.0	A
Peak Forward Surge Current	I_{FSM}	30	A
Power Dissipation	P_D	2.0	W
Operating Junction Temperature	T_J	-50 to +125	°C
Storage Temperature	T_{stg}	-50 to +150	°C
Thermal Resistance	Θ_{JA}	50	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted)

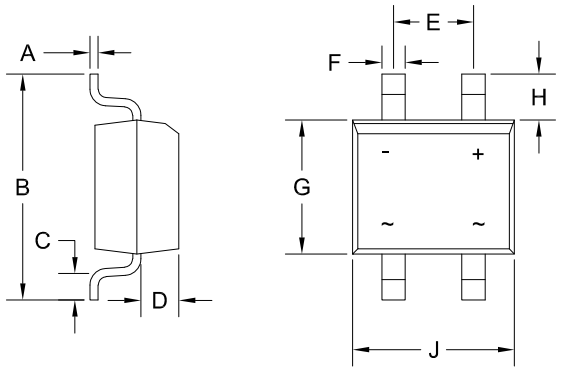
SYMBOL	**TEST CONDITIONS**	**TYP**	**MAX**	**UNITS**
I_R	V_R=40V	20	50	μA
I_R	V_R=40V, T_A=100°C	5.0	20	mA
V_F	I_F=2.0A	450	500	mV
C_J	V_R=4.0V, f=1.0MHz		250	pF

R5 (19-August 2020)

CBRHDSH2-40

SURFACE MOUNT
HIGH DENSITY
2 AMP SILICON
SCHOTTKY BRIDGE RECTIFIER

HD DIP CASE - MECHANICAL OUTLINE



R3

DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.006	0.014	0.15	0.35
B	-	0.275	-	7.00
C	0.027	0.043	0.70	1.10
D	0.035	0.051	0.90	1.30
E	0.090	0.106	2.30	2.70
F	0.019	0.031	0.50	0.80
G	0.146	0.165	3.70	4.20
H	0.051	0.067	1.30	1.70
J	0.177	0.193	4.50	4.90
K	0.090	0.106	2.30	2.70
L	0.000	0.008	0.00	0.20

HD DIP (REV: R3)

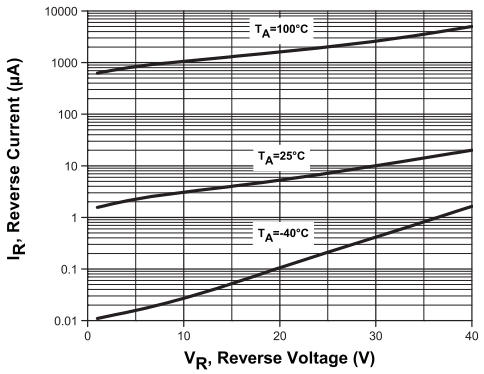
MARKING CODE: CSH2

CBRHDSH2-40

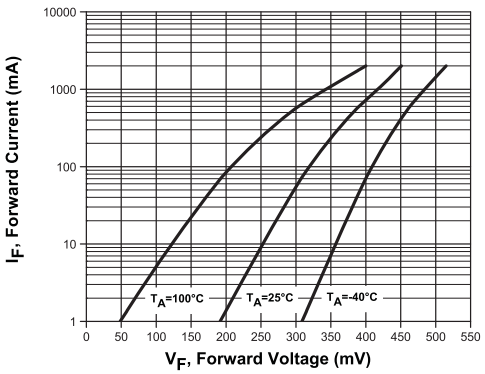
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TYPICAL ELECTRICAL CHARACTERISTICS

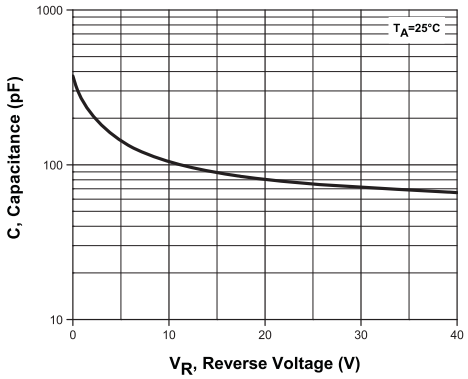
Typical Per Diode Leakage Current



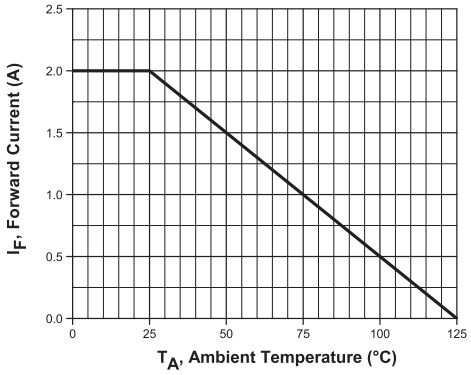
Typical Per Diode Forward Voltage



Typical Per Diode Capacitance



Per Diode Current Derating



OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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